
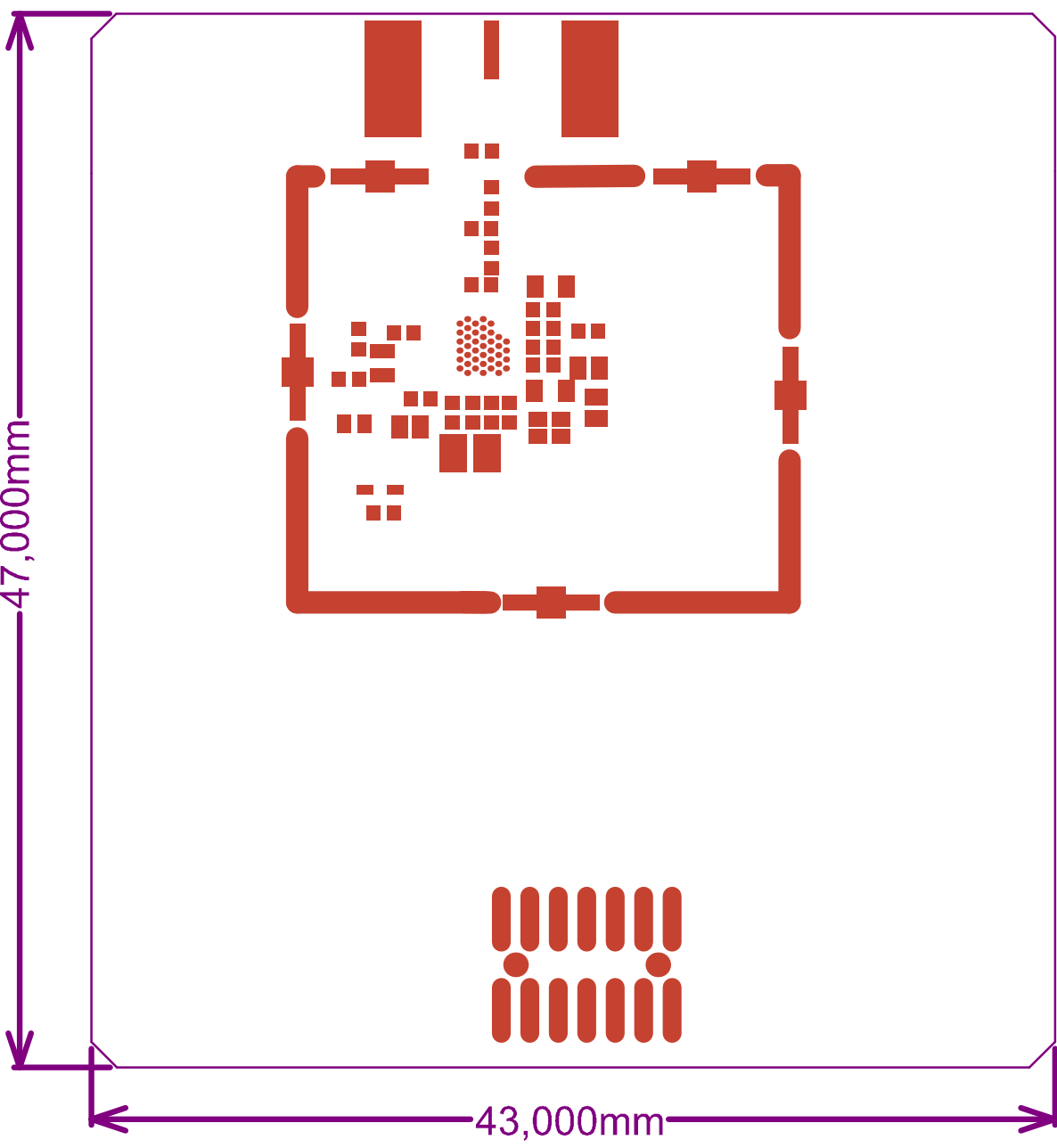

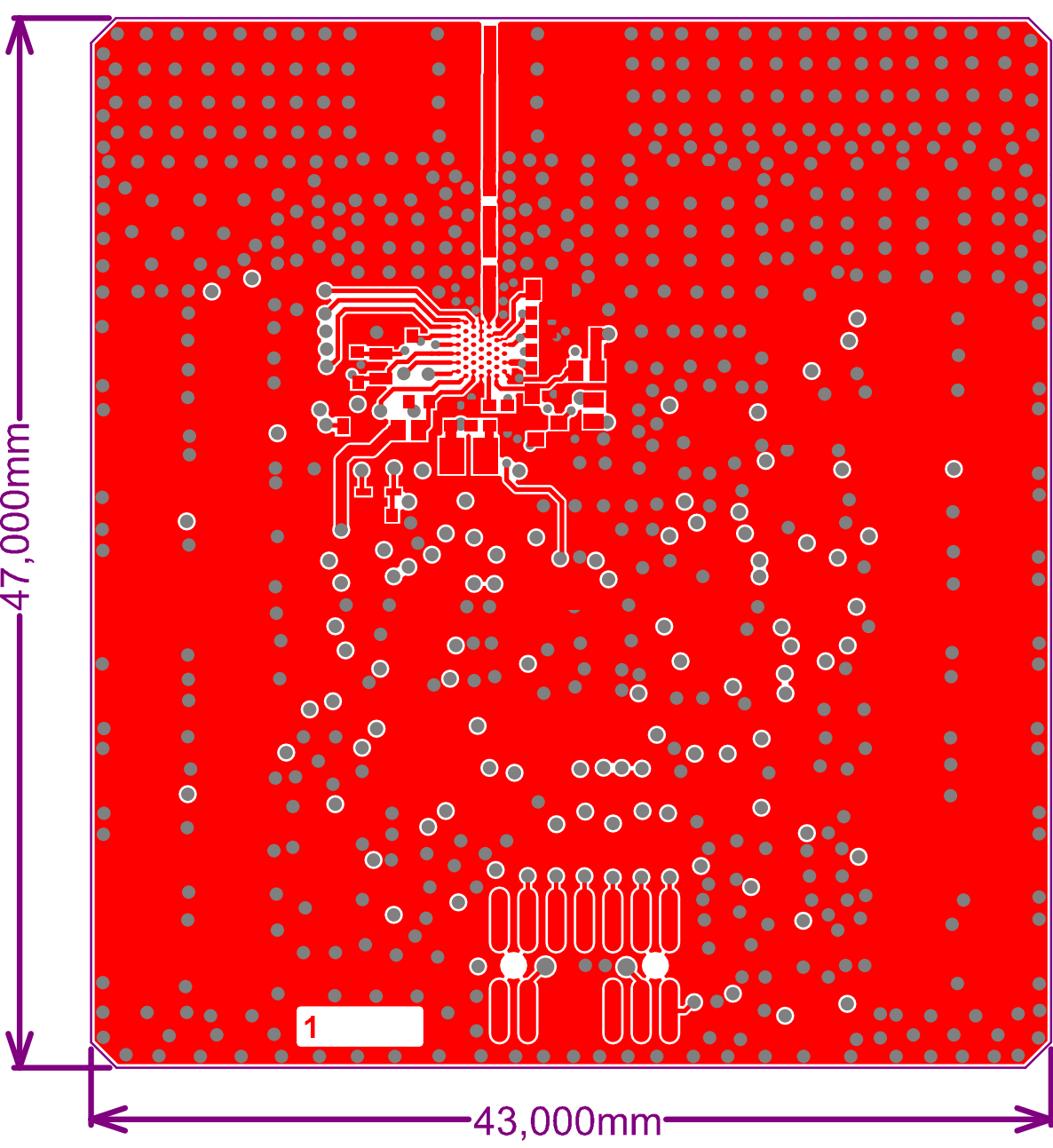



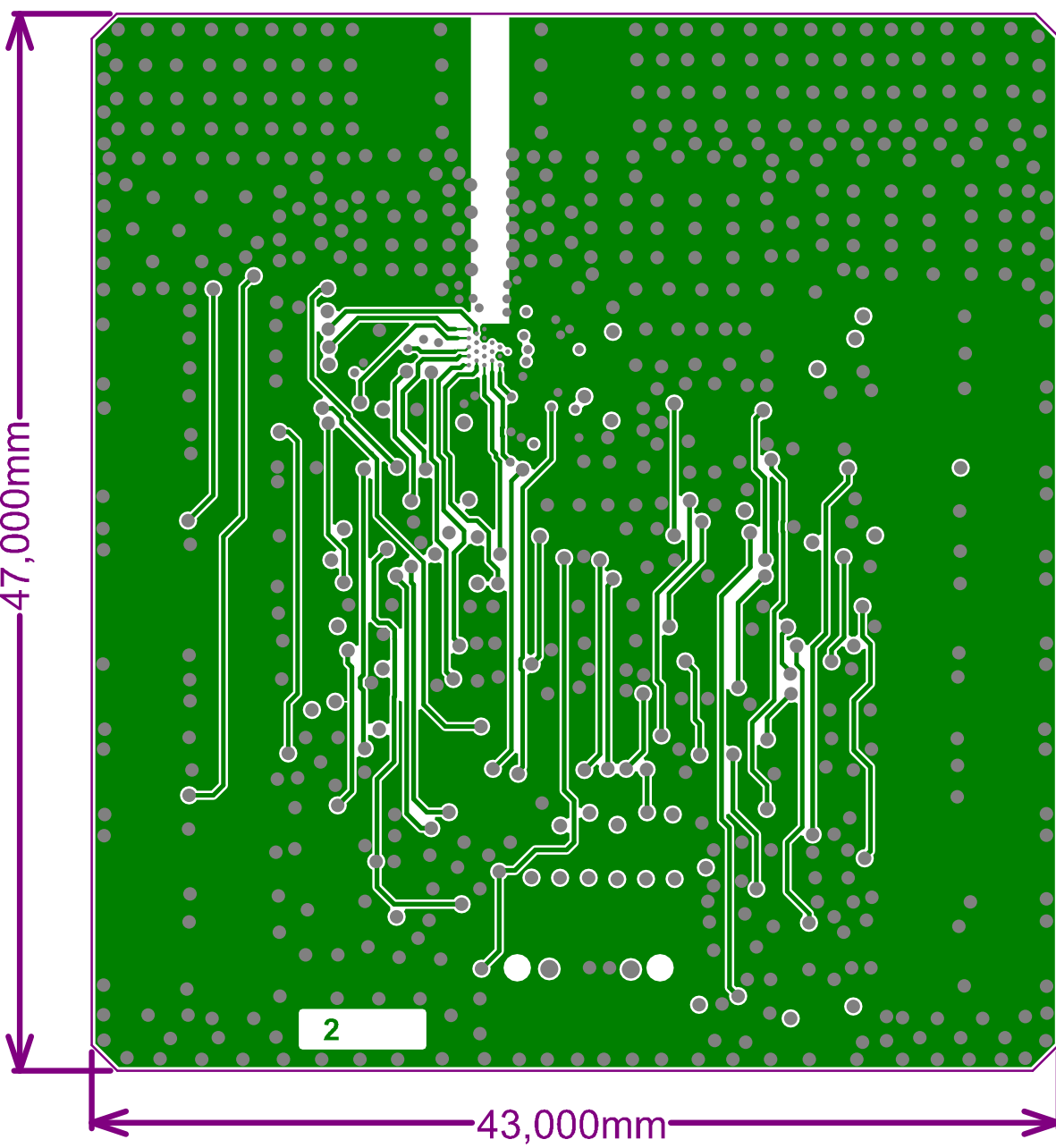
Project: MiniBoard_WBA55_WLCSP41_SMPS_SMA		
Layer: Top Overlay	Gerber: .GTO	
Variant: [No Variations]	Ref: MB2018	
Date: 29-04-2024	Rev: A	




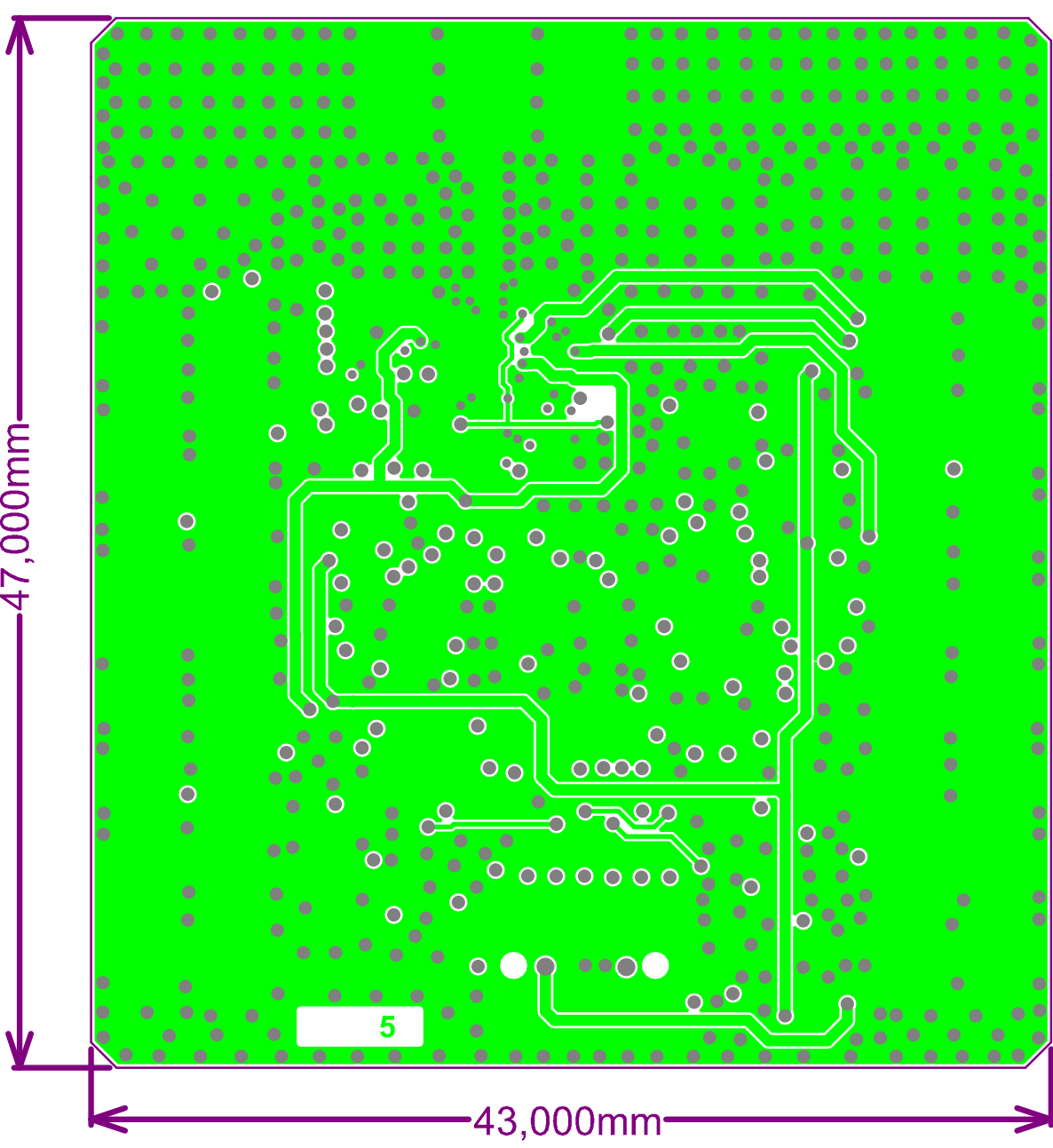
Project: MiniBoard_WBA55_WLCSP41_SMPS_SMA		
Layer: Top Solder	Gerber: .GTS	
Variant: [No Variations]	Ref: MB2018	
Date: 29-04-2024	Rev: A	




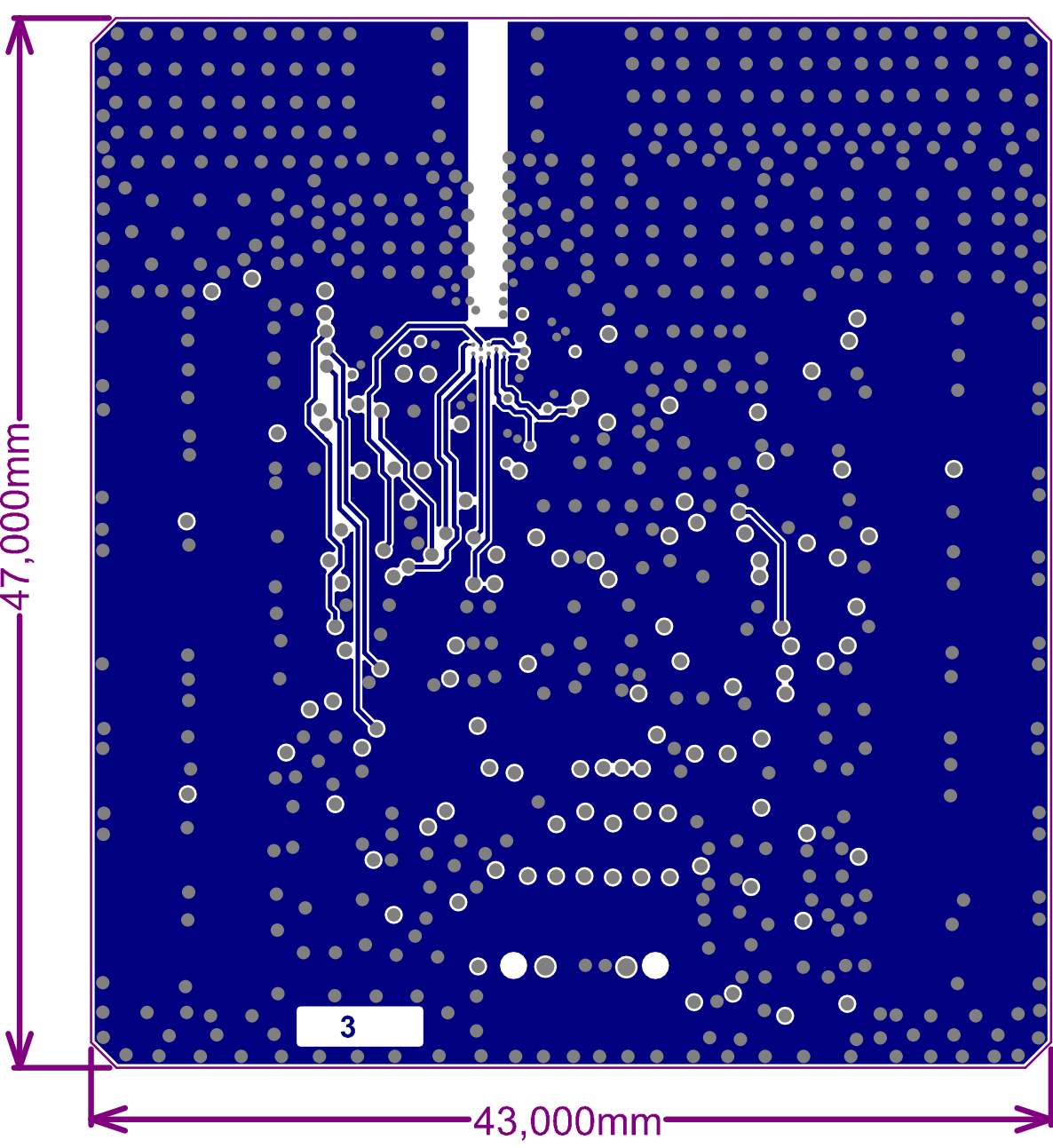
Project: MiniBoard_WBA55_WLCSP41_SMPS_SMA		
Layer: Top Layer	Gerber: .GTL	
Variant: [No Variations]	Ref: MB2018	
Date: 29-04-2024	Rev: A	




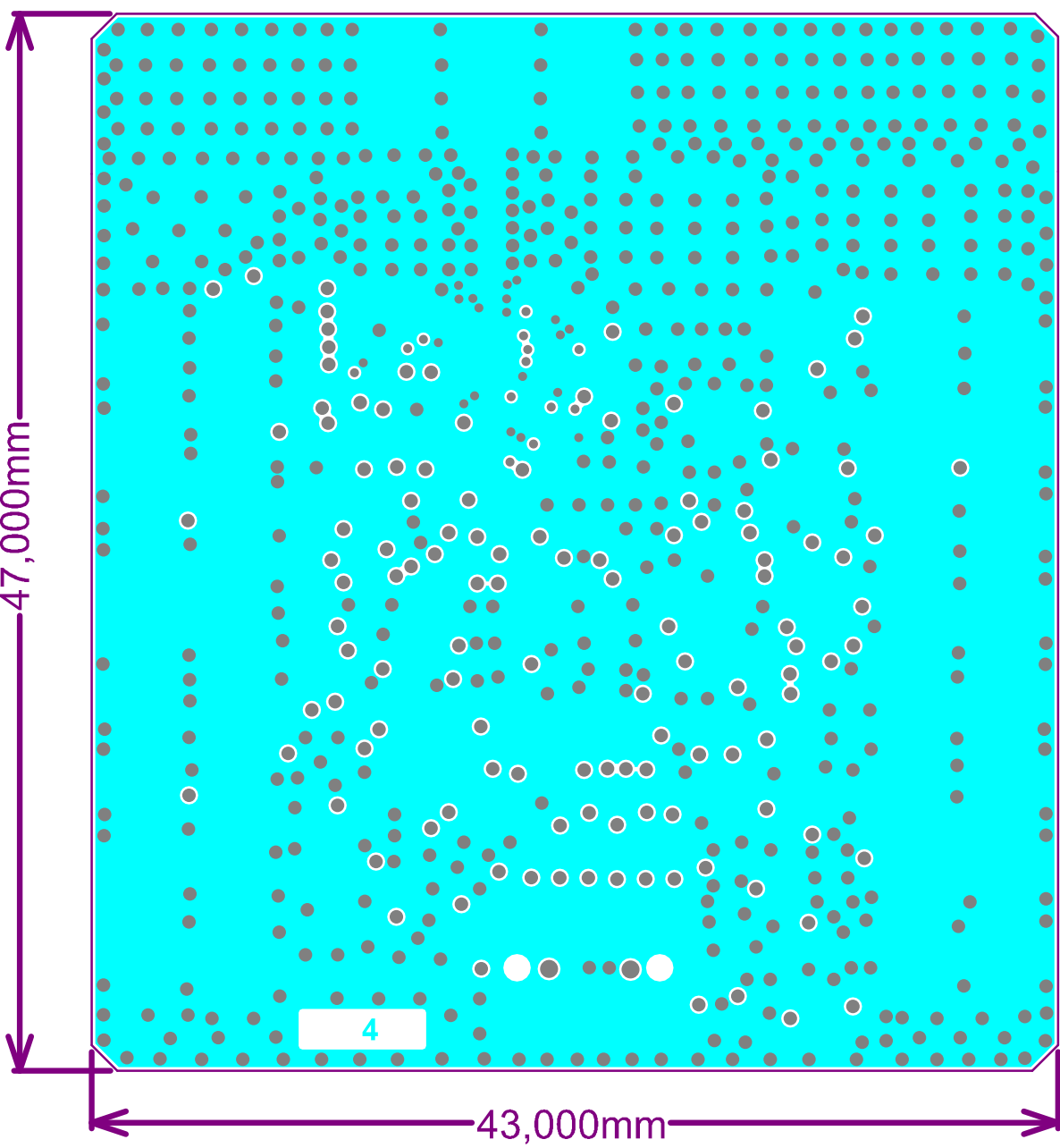
Project: MiniBoard_WBA55_WLCSP41_SMPS_SMA		
Layer: Internal 2	Gerber: .G1	
Variant: [No Variations]	Ref: MB2018	
Date: 29-04-2024	Rev: A	





Project: MiniBoard_WBA55_WLCSP41_SMPS_SMA		
Layer: Internal 5	Gerber: .G2	
Variant: [No Variations]	Ref: MB2018	
Date: 29-04-2024	Rev: A	

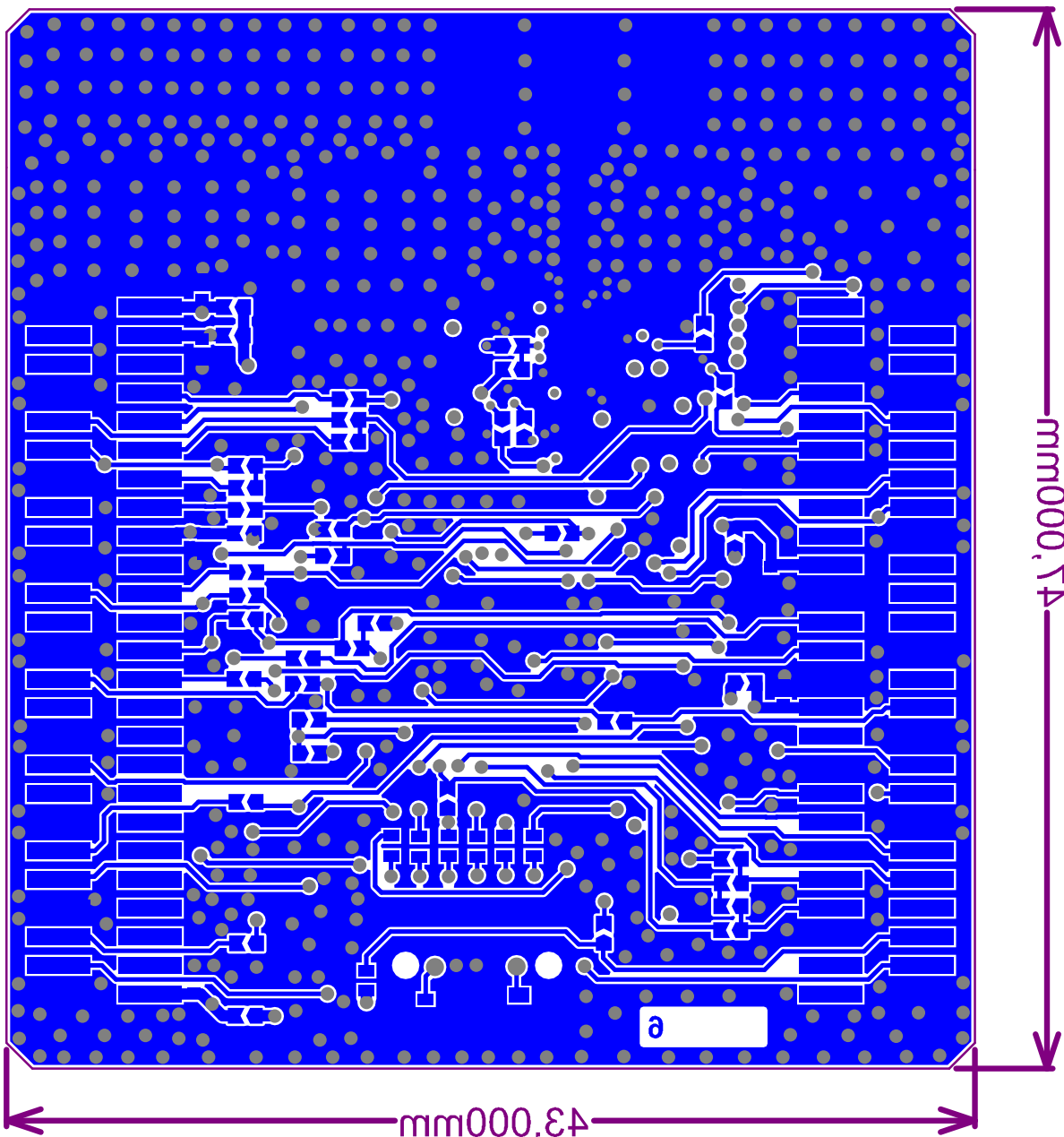



Project: MiniBoard_WBA55_WLCSP41_SMPS_SMA		
Layer:	Gerber:	
Variant: [No Variations]	Ref: MB2018	
Date: 29-04-2024	Rev: A	

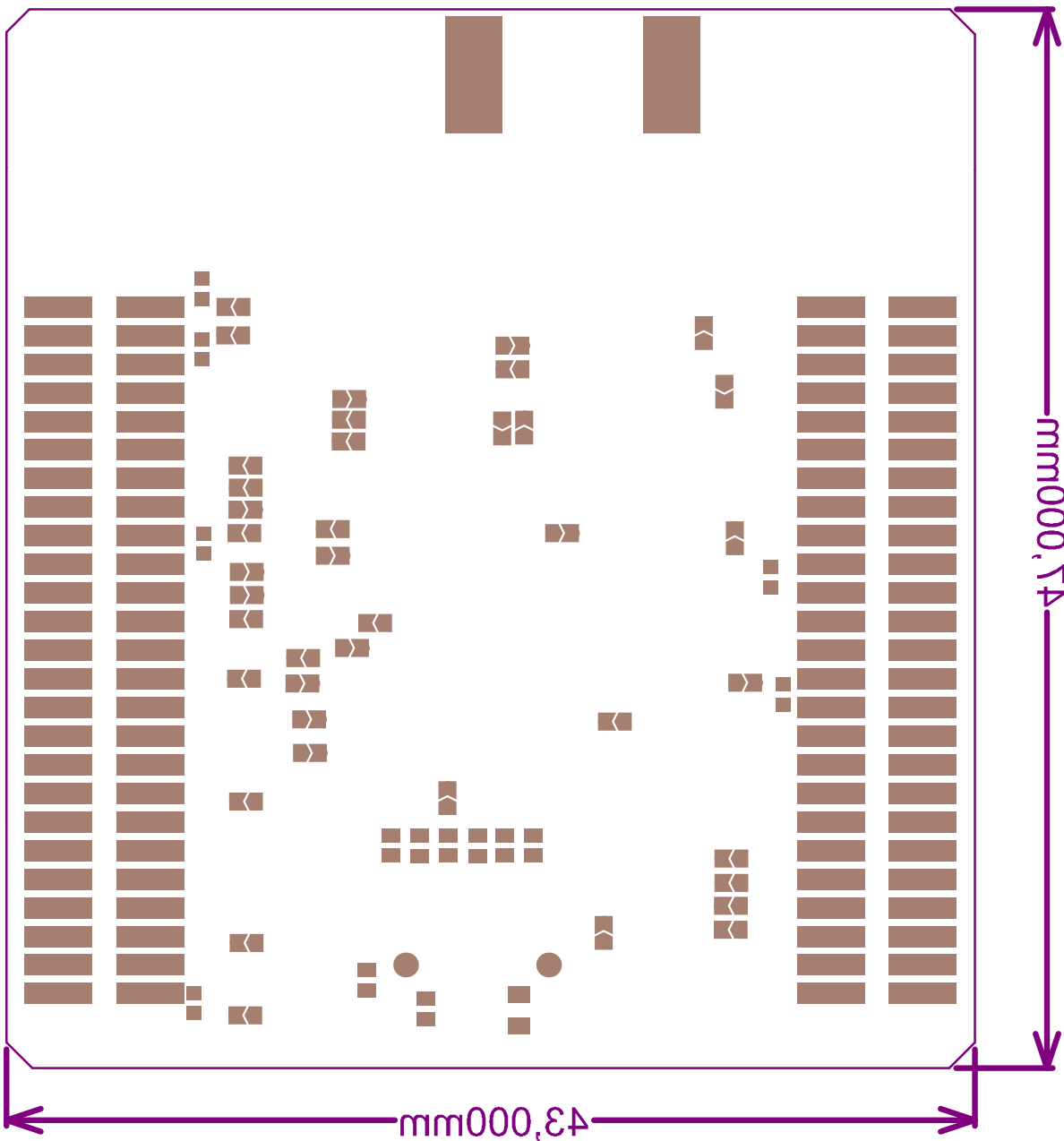



Project: MiniBoard_WBA55_WLCSP41_SMPS_SMA		
Layer:	Gerber:	
Variant: [No Variations]	Ref: MB2018	
Date: 29-04-2024	Rev: A	

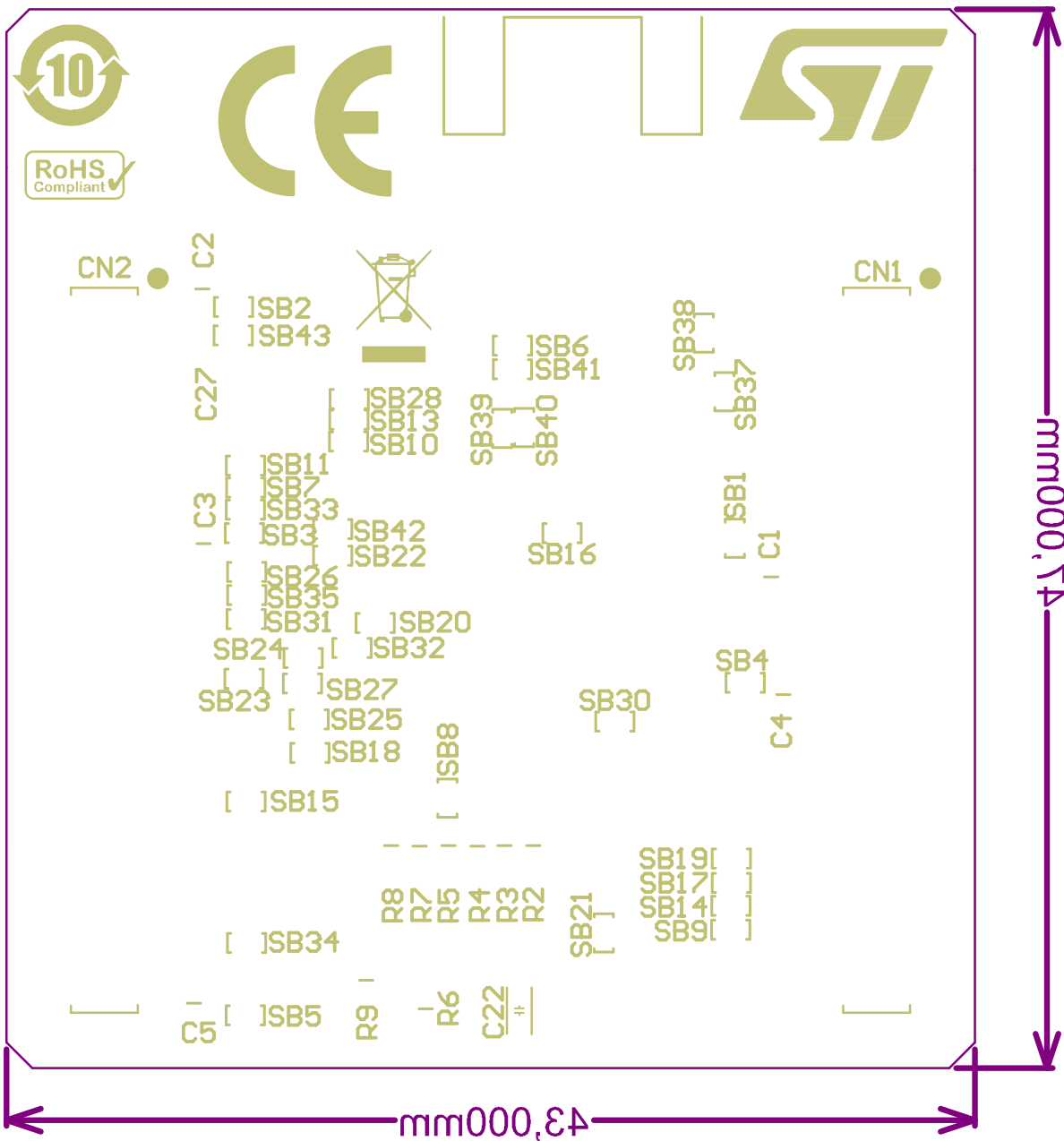
Project: MiniBoard_WBA55_WLCSP41_SMPS_SMA		
Layer: Bottom Layer	Gerber:.GBL	
Variant: [No Variations]	Ref: MB2018	
Date: 29-04-2024	Rev: A	



Project: MiniBoard_WBA55_WLCSP41_SMPS_SMA		
Layer: Bottom Solder	Gerber:.GBS	
Variant: [No Variations]	Ref: MB2018	
Date: 29-04-2024	Rev: A	



Project: MiniBoard_WBA55_WLCSP41_SMPS_SMA		
Layer: Bottom Overlay	Gerber: .GBO	
Variant: [No Variations]	Ref: MB2018	
Date: 29-04-2024	Rev: A	



IMPEDANCE TABLE					
LAYER	TRACE mils	SPACING mils	IMPEDANCE (Single ended)	IMPEDANCE (Differential)	TOL.
TOP	22.791	5.000	50 ohm	NA	+/- 10%

PCB SPECIFICATIONS :

A. MATERIAL :

FR-4

☒ TG-170

☐ TG-150

☐ TG-140

B. MATERIAL FAMILY :

N/A

C. SOLDERMASK COLOR :

☐ GREEN

☒ BLUE

☐ RED

☐ BLACK

D. SILKSCREEN COLOR :

☒ WHITE

☐ YELLOW

☐ BLACK

E. SURFACE FINISH :

☒ ENIG

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ HASL

☐ HASL (PB-FREE)

☐ GOLDEN FINGER

☐ IMPEDANCE CONTROL :

☐ NO

☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

G. THROUGH VIA :

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.

PLUG MATERIAL : ☒ SOLDERMASK

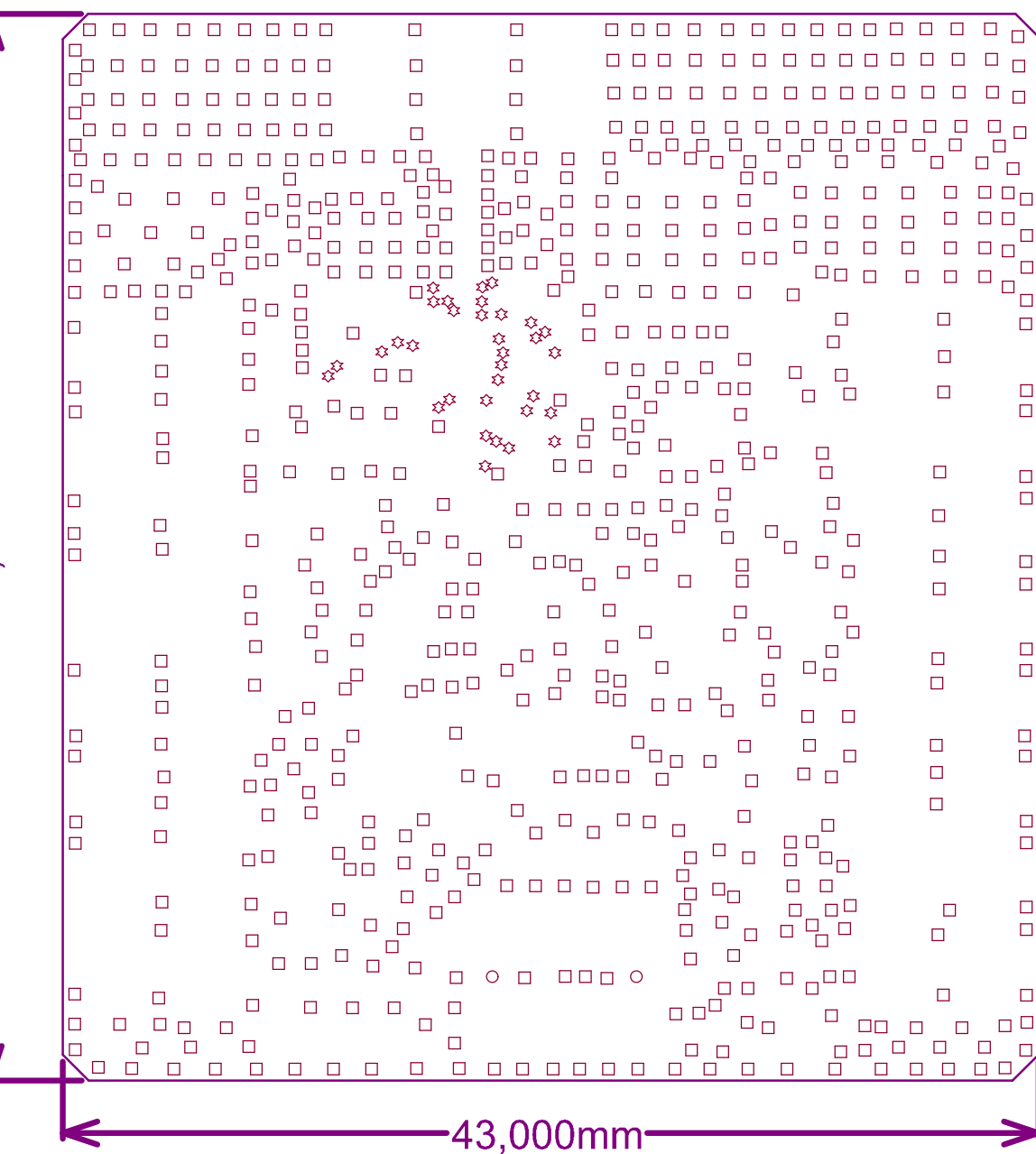
☐ NON-CONDUCTIVE EPOXY.

☐ STACK-UP :

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0,70mil	4.2	
1	Top Layer	Cu	1,40mil		
	Dielectric 1-2	Prepreg	2,70mil	3.9	
2	Internal 2	Cu	1,40mil		
	Dielectric 2-3	Prepreg	2,70mil	3.9	
3	Internal 3	Cu	1,30mil		
	Dielectric 1	Core	42,00mil	4.7	
4	Internal 4	Cu	1,30mil		
	Dielectric 3	Prepreg	2,70mil	3.9	
5	Internal 5	Cu	1,40mil		
	Dielectric 2	Prepreg	2,70mil	3.9	
6	Bottom Layer	Cu	1,40mil		
	Bottom Solder	Solder Resist	0,70mil	4.2	
	Bottom Overlay				

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)
○	2	39,37mil <1,000mm>	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn100m105p-1			
✱	33	7,87mil <0,200mm>	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v40h20m0mx0			
□	695	11,81mil <0,300mm>	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	<Mixed>			
	730 Total										



Project: MiniBoard_WBA55_WLCSP41_SMPS_SMA

Layer: Drill Drawing

Variant: [No Variations]

Date: 29-04-2024

Gerber: .DRL

Ref: MB2018

Rev: A

